



RECOMMENDED PCB BOARD LAYOUT
 PCB THICKNESS=1.60mm
 (TOP VIEW)(TOL.±0.05)

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: T110914-1A	ERIC-WU	2011.04.09
B	ECN NO:S130359	SCAN	2013.07.26
C	ECN NO:S170439-C	peng	2017.06.12

- SPECIFICATIONS:
- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1.8A (PIN1,4) ; OTHER CONTACTS 0.25A
 - CONTACT RESISTANCE: 40mΩ MAX.FOR VBUS AND PGND(B1 PIN&B4 PIN) 50mΩ MAX.(FOR OTHER PIN)
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1 MINUTE
 - INSULATION RESISTANCE: 100MΩ/MIN
 - SHELL-1 SHOULD CONTACT WITH SHELL-2
 - MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 3.5 kgf MAX
 - INITIAL : 1.0 kgf MIN, 3.5 kgf MAX
 - TEST AFTER : 0.8 kgf MIN, 3.5 kgf MAX
 - DURABILITY: 5,000 MATING CYCLES.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
 - FOR WAVE SOLDERING LEAD-FREE PROCESS.
 - DATE : YMMD
 - PACKAGING : TAPE & REEL.

Pin Number	Signal ASSIGNMENT
PIN 1	VBUS
PIN 2	D-
PIN 3	D+
PIN 4	GND
PIN 5	SID4_SSRX-
PIN 6	SID4_SSRX+
PIN 7	GND_DRAIN
PIN 8	SID4_SSTX-
PIN 9	SID4_SSTX+

J	MYLAR	1	KAPTON		9.7mm±0.13mm
I	SHELL-2	1	STAINLESS STEEL		
H	SHELL-1	1	STAINLESS STEEL		NICKEL 60μm MIN.
G	BOTTOM TERMINAL (4PIN)	4	COPPER ALLOY		
F	BOTTOM TERMINAL SPIN	5	COPPER ALLOY		GOLD FLASH PLATING ON CONTACT AREA MATT TIN 1000μm MIN ON SOLDER TAIL AREA OVERALL 50μm NICKEL UNDER PLATING
E	TOP TERMINAL 4PIN	4	COPPER ALLOY		
D	TOP TERMINAL SPIN	5	COPPER ALLOY		
C	BASE-2	1	THERMOPLASTIC		BLUE(300C)
B	BASE-1	1	THERMOPLASTIC		BLUE(300C)
A	HOUSING	1	THERMOPLASTIC		BLUE(300C)

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singtron Enterprise Co., Ltd. 信譽企業股份有限公司				
TITLE USB 3.0 CONNECTOR				
DWN	peng	PART NO.2UB3902-000101P		
CHKD	james	SCALE 1:1	UNIT: mm	
APVD	boye	SIZE: A3	SHEET:1 OF 1	REV:C

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